





Features

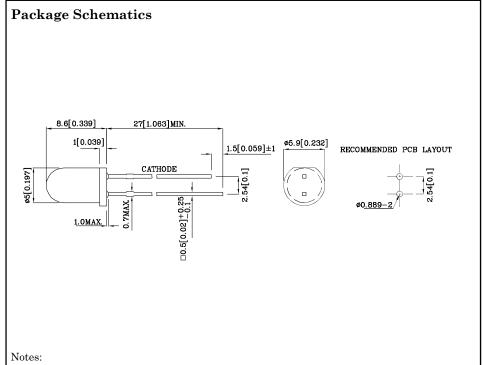
• Radial / Through hole package

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- \bullet Reliable & robust
- Low power consumption
- Available on tape and reel
- RoHS Compliant







- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)		TNI (GaAs)	Unit		
Reverse Voltage	V_{R}	5	V		
Forward Current	I_{F}	50	mA		
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	iFS	1200	mA		
Power Dissipation	P_{D}	80	mW		
Operating Temperature	$T_{\rm A}$	T _A -40 ~ +85			
Storage Temperature	Tstg	-40 ~ +85	°C		
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds				
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds				

Operating Characteristics (T _A =25°C)	TNI (GaAs)	Unit	
Forward Voltage (Typ.) (I _F =20mA)	$ m V_{F}$	1.2	V
Forward Voltage (Max.) (I _F =20mA)	$ m V_{F}$	1.6	V
Reverse Current (Max.) (V _R =5V)	$I_{ m R}$	10	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =20mA)	λΡ	940*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	$\triangle \lambda$	50	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	90	pF

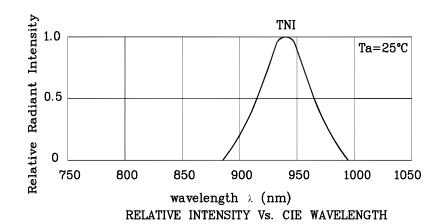
Part Number	Emitting Material	Lens-color	Radiant Intensity CIE127-2007* (Po=mW/sr) @20mA		Radiant 1 CIE127 (Po=m @50	W/sr)	Wavelength CIE127-2007* nm λP	Viewing Angle 20 1/2
			min.	typ.	min.	typ.		
XTNI12W GaAs Wate	Water Clear	15	29	55	98	- 940*	20°	
	water Clear	8*	19*	25*	49*			

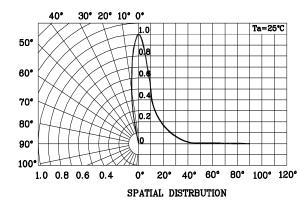
^{*}Radiant intensity value and wavelength are in accordance with CIE127-2007 standards.

Jan 03,2014 XDSA7518 V10-X Layout: Maggie L.

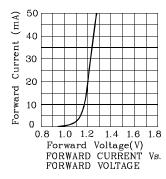


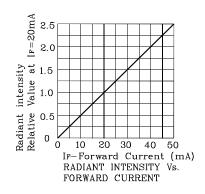


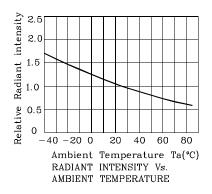




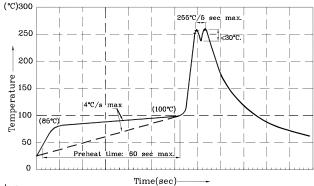
❖ TNI







Wave Soldering Profile For Thru-Hole Products (Pb-Free Components)



Notes:

- Notes. I. Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of $260^{\circ}C$ 2. Peak wave soldering temperature between $245^{\circ}C$ \sim $255^{\circ}C$ for 3 sec
- (5 sec max).
- $3.\mathrm{Do}$ not apply stress to the epoxy resin while the temperature is above $85^{\circ}\mathrm{C}$. $4.\mathrm{Fixtures}$ should not incur stress on the component when mounting and
- during soldering process. 5.SAC 305 solder alloy is recommended.
- 6. No more than one wave soldering pass

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux),

the typical accuracy of the sorting process is as follows:

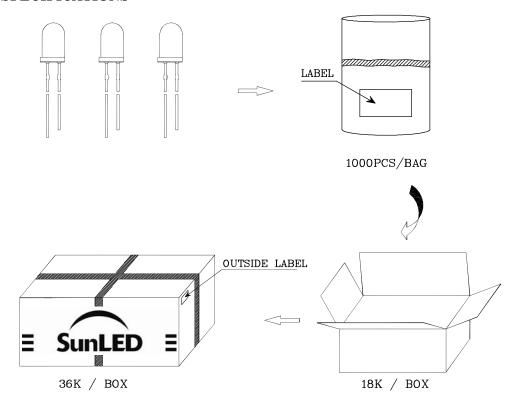
- 1. Radiant Intensity / Luminous Flux: +/-15%
- 2. Forward Voltage: +/-0.1V

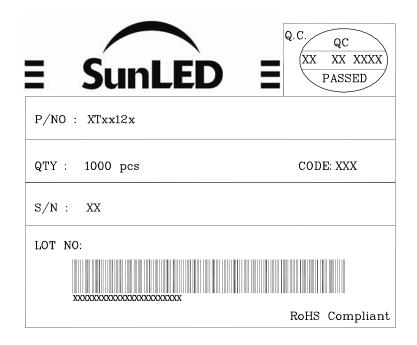
Note: Accuracy may depend on the sorting parameters.





PACKING & LABEL SPECIFICATIONS





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